Supporting next-generation 100 Gbps Ethernet and 100 Gbps InfiniBand\* Enhanced Data Rate (EDR) applications, Molex's zQSFP+ Interconnect Solution transmits up to 25 Gbps per-serial-lane data rates with excellent signal integrity (SI), electro magnetic interference (EMI) protection and thermal cooling

Molex's zQuad Small Form-factor Pluggable Plus (zQSFP+) interconnect solution is designed for high-density interconnect applications and conforms to SFF-8665 QSFP28. Components of the system include SMT connectors (series 170432); and stacked integrated 2-by-1, 2-by-2 and 2-by-3 connectors and cages (series 171565). Products scheduled for upcoming release include: copper passive cable assemblies (Series 111114); EMI cages (Series 11115) and active optical cables (Series 106412).

Molex's zQSFP+ SMT connector supports new 100 Gbps Ethernet and 100 Gbps InfiniBand\* (IB) Enhanced Data Rate (EDR) applications. EDR applications consist of four lanes of high-speed differential signals with individual data rates at 25 Gbps. The preferential coupling design uses a narrow-edge coupled, blanked- and formed-contact geometry and insert molding to optimize electrical performance. The zQSFP+ connector shares the same mating interface as the QSFP+ form factor, making it backward compatible with current connectors, cages and cable assemblies. Overall connector length is 2.20mm deeper than the current QSFP+ connector.

Soon-to-be-released zQSFP+ EMI cages will be designed with an advanced heat-sink system to provide a high level of heat dissipation for next-generation system-power levels. The spring-finger design will provide optimal EMI grounding and allow for more space to route high-speed traces.

Future low-power, integrated active optical cable (AOC) solutions will provide less expensive, reliable transport for aggregated data rates up to 100 Gbps. The singlemode fiber technology will provide long reaches of up to 4km, enabling deployment in data centers and campus environments.

## zQuad Small Formfactor Pluggable Plus (zQSFP+) Interconnect System

- 170432 SMT Connectors
- 171565 Stacked Integrated 2-by-1, 2-by-2 and 2-by-3 Connectors and Cages



zQSFP+ SMT Connector (Series 170432)



zQSFP+ Stacked, Integrated, 2-by-1 Connector and Cage (Series 171565)

## **Specifications**

#### SMT Connectors

Reference Information Packaging: Tape and Reel UL File No.: E29179 CSA File No.: LR19980 Mates With: Copper Cable Assemblies (Series 74757, 111040)

Designed In: Millimeters

### Electrical

Voltage: 30V Current: 0.5A max. Contact Resistance: 30 milliohms max. Dielectric Withstanding Voltage: 500V AC Insulation Resistance: 1000 Megohms min.

**Mechanical** 

Contact Retention to Housing: 4.45N Mating Force: 1.25N per circuit Unmating Force: 0.25N per circuit Durability:

250 cycles for  $30\mu$ " Gold (Au) plating

## Physical

Housing: High-Temperature Thermoplastic Glass Filled, UL 94V-0, Black

## **Features and Benefits**

Contact: Copper (Cu) Alloy Plating: Contact Area — 15µ" (0.38µm) or 30µ" (0.76µm) Gold (Au) Solder Tail Area — Tin (Sn) Underplating — Nickel (Ni) RoHS Compliant: Yes Operating Temperature: -40 to +80°C

#### Stacked Integrated Connectors

and Cages Reference Information Packaging: Tray UL File No.: E29179 Mates With: Copper Cable Assemblies (Series 74757, 111040) Designed In: Millimeters

### Electrical

Voltage: 30V Current: 0.5A max. Contact Resistance: 30 milliohms max. Dielectric Withstanding Voltage: 500V AC Insulation Resistance: 1000 Megohms min.

## zQuad Small Formfactor Pluggable Plus (zQSFP+) Interconnect System

#### Mechanical

Mating Force: 0.75N per circuit Unmating Force: 0.25N per circuit Durability: 100 cycles for 30µ" Gold (Au) plating

#### Physical

Housing:

High-Temperature Thermoplastic Glass Filled, UL 94V-0, Black Contact: Copper (Cu) Alloy Plating:

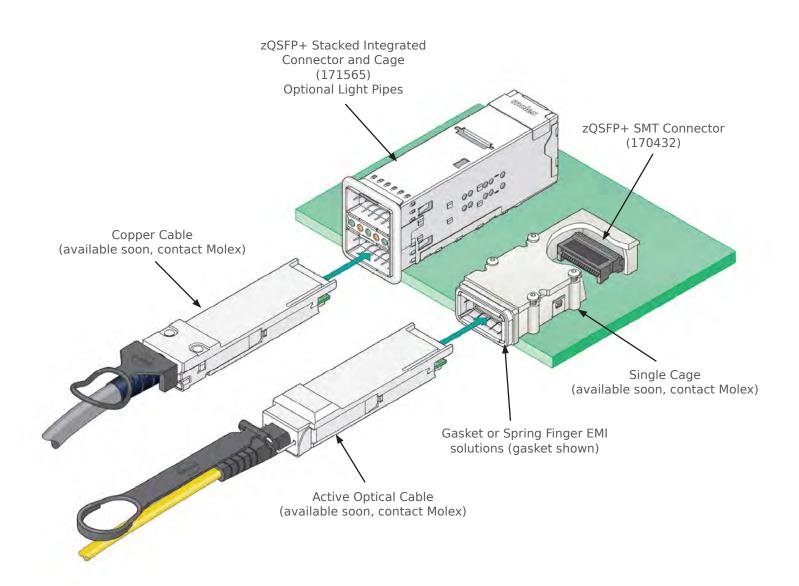
Contact Area —30µ" (0.76µm) Gold (Au)

Signal Tail Area — Tin / Lead (Sn/Pb) Underplating — Nickel (Ni) RoHS Compliant: Yes – By Exemption

Operating Temperature: -40 to +80°C

Preferential coupling design uses a narrow-edge coupled, blanked- and formed-contact geometry and insert molding	Provides superior signal integrity (SI) performance, including extremely low insertion loss (IL) of <0.8dB at a very high frequency, 14 GHz
Proven 25 Gbps data rate with potential up to 40 Gbps	Meets or exceeds current requirements for 100 Gigabit Ethernet and InfiniBand* EDR 4X applications. Supports current 10 Gbps Ethernet and 16 Gbps Fibre Channel applications. Scalable for next-generation applications
Stacked integrated connectors include an elastomeric gasket	Provides superior EMI containment
Stacked integrated connectors include a metal finger gasket	For EMI suppression
Identical mating interface as the QSFP+ connector	Backward compatible with QSFP+ form factor to extend the life of existing platforms and reduce development costs
Surface Mount Technology (SMT) design (series 170432 version only)	Allows for ease of routing and provides the option for placement on both sides of the PCB
0.80mm pitch host connector designed for placement beneath EMI cage	Ideal for pluggable applications
Stacked integrated connectors and cages are available in three sizes (2-by-1, 2-by-2 and 2-by-3)	Offers design options for high-density applications
Drop-in replacement product from TE Connectivity	Second-source option available

zQuad Small Formfactor Pluggable Plus (zQSFP+) Interconnect System



## **Applications**

**Telecommunication Equipment** 

- Hubs
- Servers
- Routers
- Switches – Central office
- Cellular infrastructure and multiplatform service systems
- Data Networking Equipment

  - Servers Storage



Data Networking Server

## zQuad Small Formfactor Pluggable Plus (zQSFP+) Interconnect System

## **Ordering Information**

### **SMT Connectors**

Order No.	Circuits	Contact Material
170432-0001		0.381µm Gold
170432-0002	38	0.762µm Gold
170432-0003		Gold Flash

### **Stacked Integrated Connectors and Cages**

Order No.	Port Size	Circuits	Light Pipe	
171565-1002	2-by-1	38 circuits per port (76 circuits total)		
171565-0002	2-by-2	38 circuits per port (152 circuits total)	– Left, Arrow Up	
171565-3002	2-by-3	38 circuits per port (230 circuits total)	Arrow Up and Down	